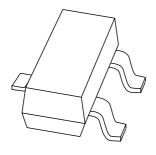
## **DISCRETE SEMICONDUCTORS**

# DATA SHEET



# BCV26; BCV46 PNP Darlington transistors

Product data sheet Supersedes data of 1999 Apr 08 2004 Jan 13



# **PNP Darlington transistors**

**BCV26**; **BCV46** 

#### **FEATURES**

- High current (max. 500 mA)
- Low voltage (max. 60 V)
- Very high DC current gain (min. 10000).

#### **APPLICATIONS**

• Where very high amplification is required.

#### **DESCRIPTION**

PNP Darlington transistor in a SOT23 plastic package. NPN complements: BCV27 and BCV47.

#### **MARKING**

TYPE NUMBER	MARKING CODE <sup>(1)</sup>
BCV26	FD*
BCV46	FE*

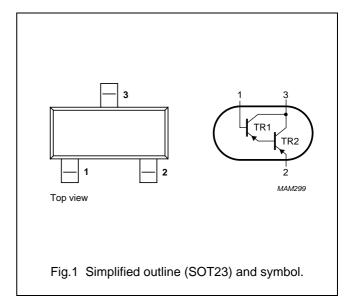
#### Note

\* = p : Made in Hong Kong.
 \* = t : Made in Malaysia.

\* = W : Made in China.

#### **PINNING**

PIN	DESCRIPTION
1	base
2	emitter
3	collector



#### **ORDERING INFORMATION**

TYPE	PACKAGE				
NUMBER	NAME	ME DESCRIPTION VERSIO			
BCV26	_	plastic surface mounted package; 3 leads			
BCV46					

# PNP Darlington transistors

BCV26; BCV46

#### **LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter			
	BCV26		_	-40	V
	BCV46		_	-80	V
V <sub>CES</sub>	collector-emitter voltage	V <sub>BE</sub> = 0			
	BCV26		_	-30	V
	BCV46		_	-60	V
V <sub>EBO</sub>	emitter-base voltage	open collector	-	-10	٧
I <sub>C</sub>	collector current (DC)		_	-500	mA
I <sub>CM</sub>	peak collector current		_	-800	mA
I <sub>B</sub>	base current (DC)		_	-100	mA
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C; note 1	_	250	mW
T <sub>stg</sub>	storage temperature		-65	+150	°C
Tj	junction temperature		_	150	°C
T <sub>amb</sub>	operating ambient temperature		-65	+150	°C

#### Note

#### THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R <sub>th(j-a)</sub>	thermal resistance from junction to ambient	note 1	500	K/W

#### Note

1. Transistor mounted on an FR4 printed-circuit board.

<sup>1.</sup> Transistor mounted on an FR4 printed-circuit board.

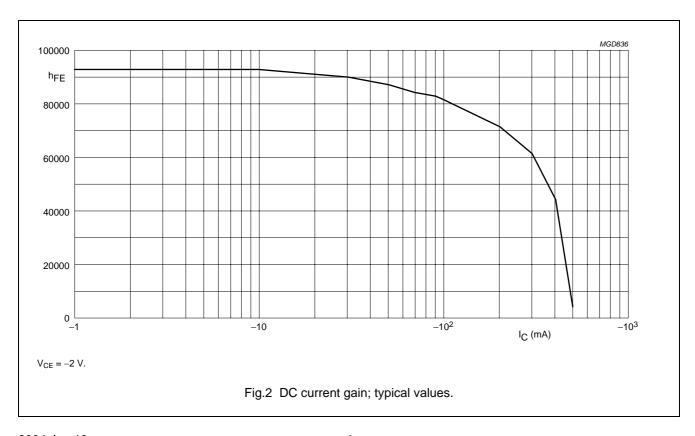
# PNP Darlington transistors

BCV26; BCV46

#### **CHARACTERISTICS**

 $T_{amb}$  = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I <sub>CBO</sub>	collector cut-off current					
	BCV26	$I_E = 0; V_{CB} = -30 \text{ V}$	_	_	-100	nA
	BCV46	$I_E = 0; V_{CB} = -60 \text{ V}$	_	_	-100	nA
I <sub>EBO</sub>	emitter cut-off current	$I_C = 0; V_{EB} = -10 \text{ V}$	_	_	-100	nA
h <sub>FE</sub>	DC current gain	$I_C = -1 \text{ mA}; V_{CE} = -5 \text{ V}; \text{ (see Fig.2)}$				
	BCV26		4000	_	_	
	BCV46		2000	_	_	
	DC current gain	$I_C = -10 \text{ mA}; V_{CE} = -5 \text{ V}; \text{ (see Fig.2)}$				
	BCV26		10000	_	_	
	BCV46		4000	_	_	
	DC current gain	$I_C = -100 \text{ mA}; V_{CE} = -5 \text{ V}; \text{ (see Fig.2)}$				
	BCV26		20000	_	_	
	BCV46		10000	_	_	
V <sub>CEsat</sub>	collector-emitter saturation voltage	$I_C = -100 \text{ mA}; I_B = -0.1 \text{ mA}$	_	_	-1	٧
V <sub>BEsat</sub>	base-emitter saturation voltage	$I_C = -100 \text{ mA}; I_B = -0.1 \text{ mA}$	_	_	-1.5	V
V <sub>BEon</sub>	base-emitter on-state voltage	$I_C = -10 \text{ mA}; V_{CE} = -5 \text{ V}$	_	_	-1.4	V
$f_{T}$	transition frequency	$I_C = -30 \text{ mA}; V_{CE} = -5 \text{ V}; f = 100 \text{ MHz}$	_	220	_	MHz



# PNP Darlington transistors

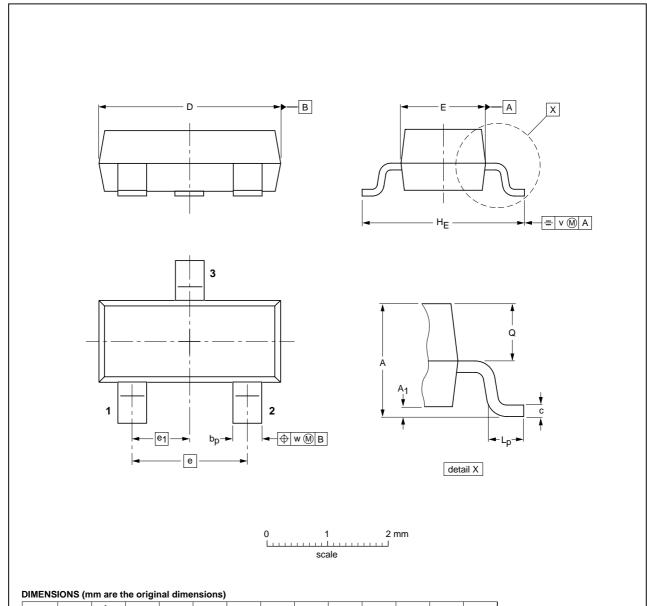
BCV26; BCV46

#### **PACKAGE OUTLINE**

UNIT

#### Plastic surface-mounted package; 3 leads

SOT23



OUTLINE	REFERENCES		EUROPEAN	ICCUE DATE		
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOT23		TO-236AB				<del>-04-11-04-</del> 06-03-16

 $\mathsf{L}_\mathsf{p}$ 

0.45

0.55

0.1

 $\mathbf{H}_{\mathbf{E}}$ 

2004 Jan 13 5

bp

0.38

max

0.9

# PNP Darlington transistors

BCV26; BCV46

#### **DATA SHEET STATUS**

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

#### **Notes**

- 1. Please consult the most recently issued document before initiating or completing a design.
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#### **Customer notification**

This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

#### **Contact information**

For additional information please visit: http://www.nxp.com
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